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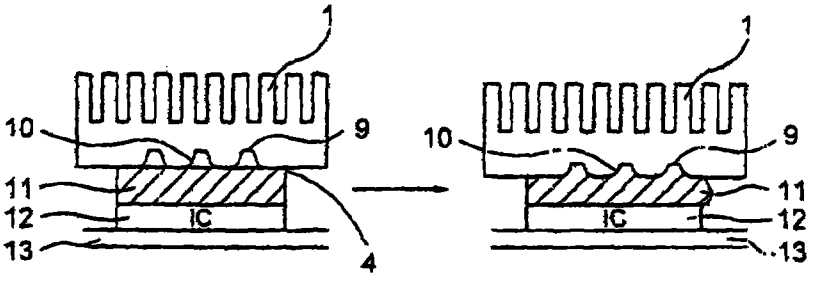
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(54) Title: HEAT SINK INCLUDING HEAT RECEIVING SURFACE WITH PROTRUDING PORTION



(57) Abstract: A heat sink includes a heat receiving surface having a plurality of protruding portions, the heat receiving surface of which is thermally connected to a heat generating component through a heat transfer rubber, to receive heat from the heat generating component and then dissipate the heat.

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